L Number	Hits	Search Text	DB	Time stamp
1	128	silicide near12 bond$3	US-PGPUB	2004/07/23 14:14
2	18	(silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3)	US-PGPUB	2004/07/23 14:14
3	110	(silicide near12 bond$3) not ((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3))	US-PGPUB	2004/07/23 14:12
4	103	((silicide near12 bond$3) not ((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3))) and (silicon wafer Si)	US-PGPUB	2004/07/23 14:13
5	56	((silicide near12 bond$3) not ((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3))) and (bond$3 near12 (substrate wafer))	US-PGPUB	2004/07/23 14:14
6	970	silicide near12 bond$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 14:14
7	140	(silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 14:15
8	122	((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3)) not ((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 14:15
9	1	238066.URPN.	USPAT	2004/07/23 14:19
10	31	4826787.URPN.	USPAT	2004/07/23 14:22
11	14	4826787.URPN. and silicide	USPAT	2004/07/23 14:32
12	5	((polish$3 CMP) near10 (metal cobalt tungsten titantium palladium W Co Ti Pd Pt platinum)) and ((silicide near12 bond$3) near20 (thermal thermally anneal$4 heat$3 bak$3))	USPAT	2004/07/23 14:34
13	25	5387555.URPN.	USPAT	2004/07/23 14:36
14	13	5387555.URPN. and silicide	USPAT	2004/07/23 14:37

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